

SGM7229

High-Speed USB 2.0 (480Mbps) DPDT Analog Switch

GENERAL DESCRIPTION

The SGM7229 is a high-speed, low-power double-pole/double-throw (DPDT) analog switch that operates from a single 1.8V to 5.5V power supply.

The SGM7229 is designed for the switching of high-speed USB 2.0 signals in handset and consumer applications, such as cell phones, digital cameras, and notebooks with hubs or controllers with limited USB I/Os.

The SGM7229 has low bit-to-bit skew and high channel-to-channel noise isolation, and is compatible with various standards, such as high-speed USB 2.0 (480Mbps). Each switch is bidirectional and offers little or no attenuation of the high-speed signals at the outputs. Its bandwidth is wide enough to pass high-speed USB 2.0 differential signals (480Mbps) with good signal integrity.

The SGM7229 contains special circuitry on the D+/D- pins which allows the device to withstand a V_{BUS} short to D+ or D- when the USB devices are either powered off or powered on.

The SGM7229 is available in Green MSOP-10 and UTQFN-1.8×1.4-10L packages. It operates over an ambient temperature range of -40°C to +85°C.

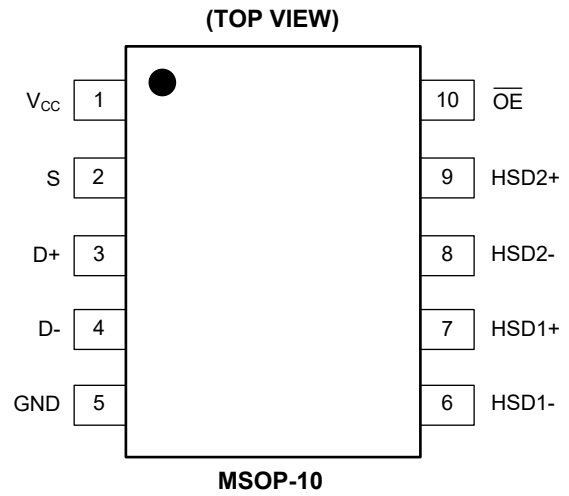
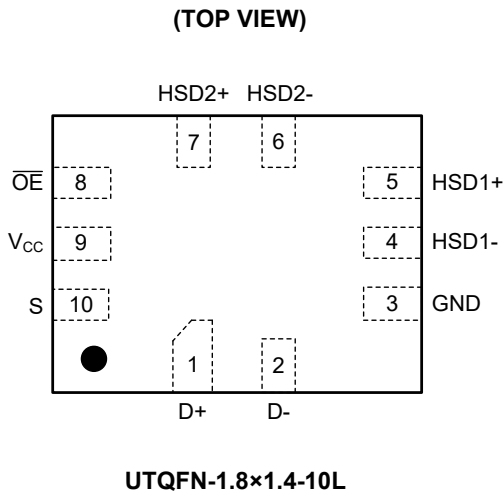
FEATURES

- **Supply Voltage Range: 1.8V to 5.5V**
- **On-Resistance: 5.5Ω (TYP) at 3V**
- **Fast Switching Times:**
 - $t_{ON} = 40\text{ns}$
 - $t_{OFF} = 15\text{ns}$
- **Crosstalk: -20dB at 250MHz**
- **Off-Isolation: -22dB at 250MHz**
- **Rail-to-Rail Input and Output Operation**
- **Break-Before-Make Switching**
- **-40°C to +85°C Operating Temperature Range**
- **Available in Green UTQFN-1.8×1.4-10L and MSOP-10 Packages**

APPLICATIONS

Route Signals for USB 2.0
MP3 and Other Personal Media Players
Digital Cameras and Camcorders
Portable Instrumentation
Set-Top Box
PDAs

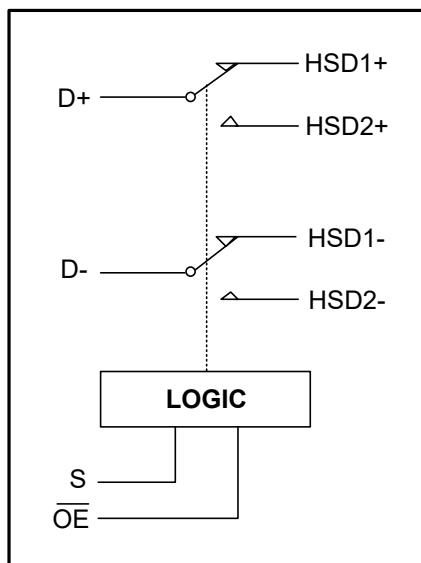
PIN CONFIGURATIONS



PIN DESCRIPTION

PIN		NAME	FUNCTION
UTQFN-1.8x1.4-10L	MSOP-10		
1	3	D+	USB Data Bus.
2	4	D-	USB Data Bus.
3	5	GND	Ground.
4	6	HSD1-	Multiplexed Source Input.
5	7	HSD1+	Multiplexed Source Input.
6	8	HSD2-	Multiplexed Source Input.
7	9	HSD2+	Multiplexed Source Input.
8	10	\overline{OE}	Output Enable.
9	1	V _{CC}	Power Supply.
10	2	S	Select Input.

BLOCK DIAGRAM



FUNCTION TABLE

\overline{OE}	S	HSD1+, HSD1-	HSD2+, HSD2-
0	0	ON	OFF
0	1	OFF	ON
1	x	OFF	OFF

NOTE: Switches shown for logic "0" input.

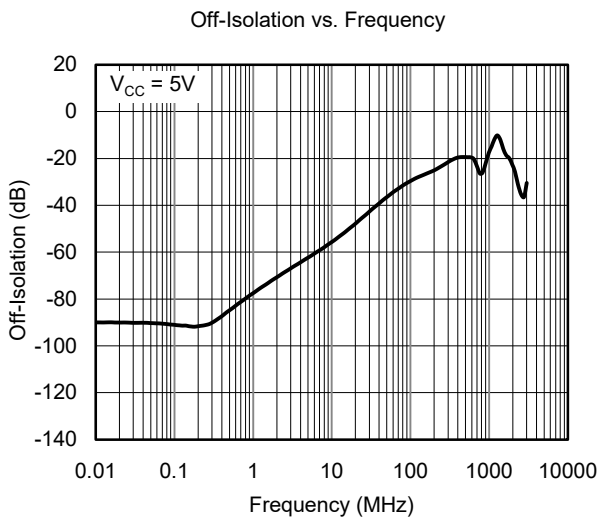
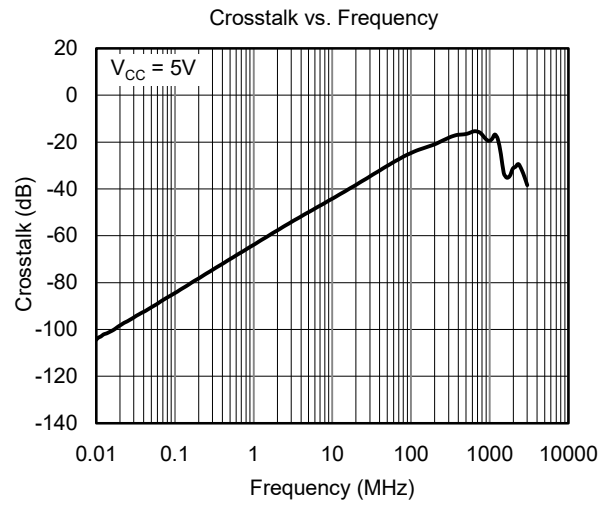
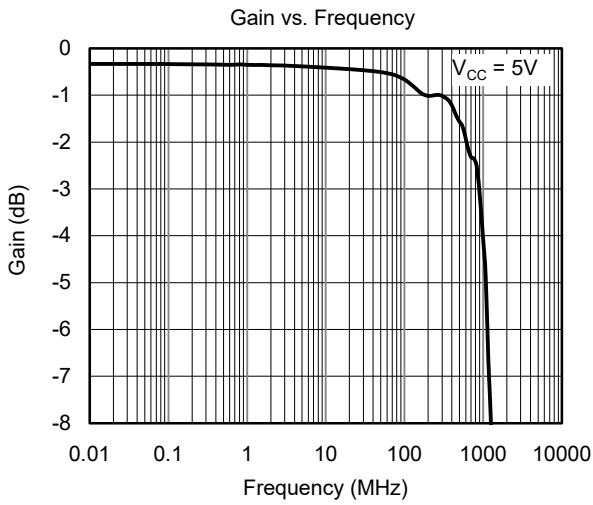
ELECTRICAL CHARACTERISTICS(V_{CC} = 3.3V, Full = -40°C to +85°C, typical values are at T_A = +25°C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	TEMP	MIN	TYP	MAX	UNITS
ANALOG SWITCH							
Analog I/O Voltage (HSD1+, HSD1-, HSD2+, HSD2-)	V _{IS}		Full	0		V _{CC}	V
On-Resistance	R _{ON}	V _{CC} = 3V, V _{IS} = 0V to 0.4V, I _D = 8mA, Test Circuit 1	+25°C		5.5	7	Ω
			Full			8	
On-Resistance Match between Channels	ΔR _{ON}	V _{CC} = 3V, V _{IS} = 0V to 0.4V, I _D = 8mA, Test Circuit 1	+25°C		0.2	0.75	Ω
			Full			0.9	
On-Resistance Flatness	R _{FLAT(ON)}	V _{CC} = 3V, V _{IS} = 0V to 1V, I _D = 8mA, Test Circuit 1	+25°C		2	3	Ω
			Full			3.5	
Power Off Leakage Current (D+, D-)	I _{OFF}	V _{CC} = 0V, V _D = 0V to 3.6V, V _S , V _{OE} = 0V or 3.6V	+25°C		0.1	0.3	μA
			Full			0.5	
Increase in I _{CC} per Control Voltage	I _{CCT}	V _{CC} = 3.6V, V _S or V _{OE} = 1.8V	+25°C		2	3	μA
			Full			3.5	
Source Off Leakage Current	I _{HSD2(OFF)} , I _{HSD1(OFF)}	V _{CC} = 3.6V, V _{IS} = 3.3V/0.3V, V _D = 0.3V/3.3V	+25°C		0.1	0.3	μA
			Full			0.5	
Channel On Leakage Current	I _{HSD2(ON)} , I _{HSD1(ON)}	V _{CC} = 3.6V, V _{IS} = 3.3V/0.3V, V _D = 3.3V/0.3V or floating	+25°C		0.1	0.3	μA
			Full			0.5	
DIGITAL INPUTS							
Input High Voltage	V _{IH}		Full	1.5			V
Input Low Voltage	V _{IL}		Full			0.4	V
Input Leakage Current	I _{IN}	V _S , V _{OE} = 0V or V _{CC}	+25°C		0.1	0.3	μA
			Full			0.5	
DYNAMIC CHARACTERISTICS							
Turn-On Time	t _{ON}	V _{IS} = 0.8V, R _L = 50Ω, C _L = 10pF, Test Circuit 2	+25°C		40		ns
Turn-Off Time	t _{OFF}		+25°C		15		ns
Break-Before-Make Time Delay	t _D	V _{IS} = 0.8V, R _L = 50Ω, C _L = 10pF, Test Circuit 3	+25°C		20		ns
Propagation Delay	t _{PD}	R _L = 50Ω, C _L = 10pF	+25°C		0.5		ns
Off Isolation	O _{ISO}	Signal = 0dBm, R _L = 50Ω, f = 250MHz, Test Circuit 4	+25°C		-22		dB
Channel-to-Channel Crosstalk	X _{TALK}	Signal = 0dBm, R _L = 50Ω, f = 250MHz, Test Circuit 5	+25°C		-20		dB
-3dB Bandwidth	BW	Signal = 0dBm, R _L = 50Ω, C _L = 5pF, Test Circuit 6	+25°C		850		MHz
Channel-to-Channel Skew	t _{SKEW}	R _L = 50Ω, C _L = 10pF	+25°C		0.5		ns
Charge Injection Select Input to Common I/O	Q	V _G = GND, C _L = 1nF, R _G = 0Ω, Q = C _L × V _{OUT} , Test Circuit 7	+25°C		2		pC
HSD+, HSD-, D+, D- On-Capacitance	C _{ON}	f = 1MHz	+25°C		6		pF
			+25°C		6		

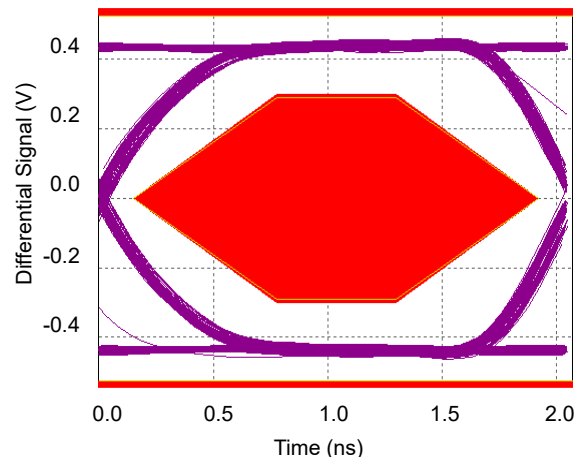
ELECTRICAL CHARACTERISTICS (continued)(V_{CC} = 5V, Full = -40°C to +85°C, typical values are at T_A = +25°C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	TEMP	MIN	TYP	MAX	UNITS
ANALOG SWITCH							
Analog I/O Voltage (HSD1+, HSD1-, HSD2+, HSD2-)	V _{IS}		Full	0		V _{CC}	V
On-Resistance	R _{ON}	V _{IS} = 0V to 0.4V, I _D = 8mA, Test Circuit 1	+25°C		4.5	5.5	Ω
			Full			6	
On-Resistance Match between Channels	ΔR _{ON}	V _{IS} = 0V to 0.4V, I _D = 8mA, Test Circuit 1	+25°C		0.2	0.65	Ω
			Full			0.7	
On-Resistance Flatness	R _{FLAT(ON)}	V _{IS} = 0V to 1V, I _D = 8mA, Test Circuit 1	+25°C		0.5	0.75	Ω
			Full			0.9	
Power Off Leakage Current (D+, D-)	I _{OFF}	V _{CC} = 0V, V _D = 0V to 5.5V, V _S , V _{OE} = 0V or 5.5V	+25°C		0.1	0.3	μA
			Full			0.5	
Increase in I _{CC} per Control Voltage	I _{CC} T	V _{CC} = 5.5V, V _S or V _{OE} = 1.8V	+25°C		14	18	μA
			Full			22	
Source Off Leakage Current	I _{HSD2(OFF)} , I _{HSD1(OFF)}	V _{CC} = 5.5V, V _{IS} = 4.5V/1V, V _D = 1V/4.5V	+25°C		0.1	0.3	μA
			Full			0.5	
Channel On Leakage Current	I _{HSD2(ON)} , I _{HSD1(ON)}	V _{CC} = 5.5V, V _{IS} = 4.5V/1V, V _D = 4.5V/1V or floating	+25°C		0.1	0.3	μA
			Full			0.5	
DIGITAL INPUTS							
Input High Voltage	V _{IH}	V _{CC} = 5.5V	Full	1.8			V
Input Low Voltage	V _{IL}	V _{CC} = 5.5V	Full			0.6	V
Input Leakage Current	I _{IN}	V _{CC} = 5.5V, V _S , V _{OE} = 0V or V _{CC}	+25°C		0.1	0.3	μA
			Full			0.5	
DYNAMIC CHARACTERISTICS							
Turn-On Time	t _{ON}	V _{IS} = 0.8V, R _L = 50Ω, C _L = 10pF, Test Circuit 2	+25°C		40		ns
Turn-Off Time	t _{OFF}		+25°C		15		ns
Break-Before-Make Time Delay	t _D	V _{IS} = 0.8V, R _L = 50Ω, C _L = 10pF, Test Circuit 3	+25°C		20		ns
Propagation Delay	t _{PD}	R _L = 50Ω, C _L = 10pF	+25°C		0.5		ns
Off Isolation	O _{ISO}	Signal = 0dBm, R _L = 50Ω, f = 250MHz, Test Circuit 4	+25°C		-22		dB
Channel-to-Channel Crosstalk	X _{TALK}	Signal = 0dBm, R _L = 50Ω, f = 250MHz, Test Circuit 5	+25°C		-20		dB
-3dB Bandwidth	BW	Signal = 0dBm, R _L = 50Ω, C _L = 5pF, Test Circuit 6	+25°C		850		MHz
Channel-to-Channel Skew	t _{SKEW}	R _L = 50Ω, C _L = 10pF	+25°C		0.5		ns
Charge Injection Select Input to Common I/O	Q	V _G = GND, C _L = 1nF, R _G = 0Ω, Q = C _L × V _{OUT} , Test Circuit 7	+25°C		2		pC
HSD+, HSD-, D+, D- On-Capacitance	C _{ON}	f = 1MHz	+25°C		6		pF
			+25°C			6	
POWER REQUIREMENTS							
Power Supply Range	V _{CC}		Full	1.8		5.5	V
Power Supply Current	I _{CC}	V _{CC} = 5.5V, V _S , V _{OE} = 0V or V _{CC}	+25°C		0.1	0.3	μA
			Full			0.5	

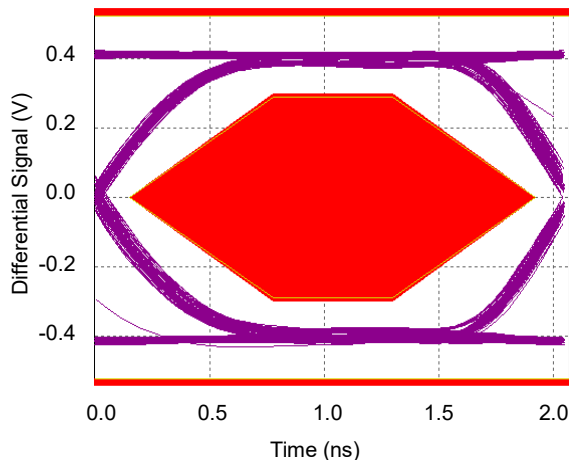
TYPICAL PERFORMANCE CHARACTERISTICS



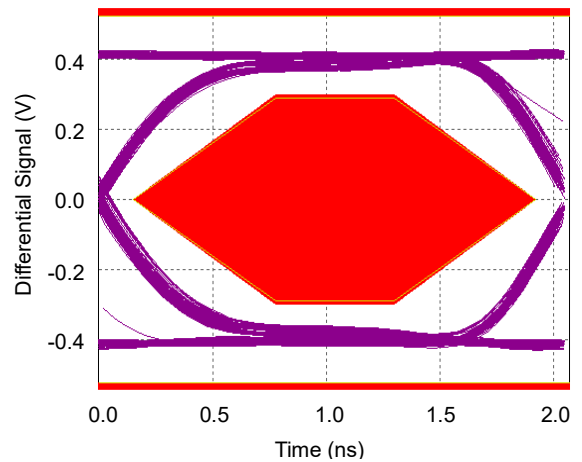
Eye Pattern: 480Mbps USB 2.0 Signal with No Switch (Through Path)



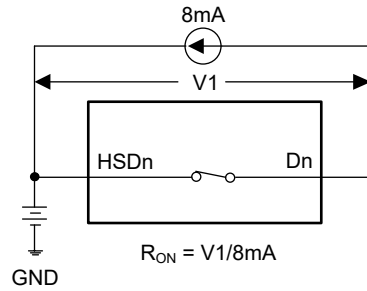
Eye Pattern: 480Mbps USB 2.0 Signal with Switch NO Path



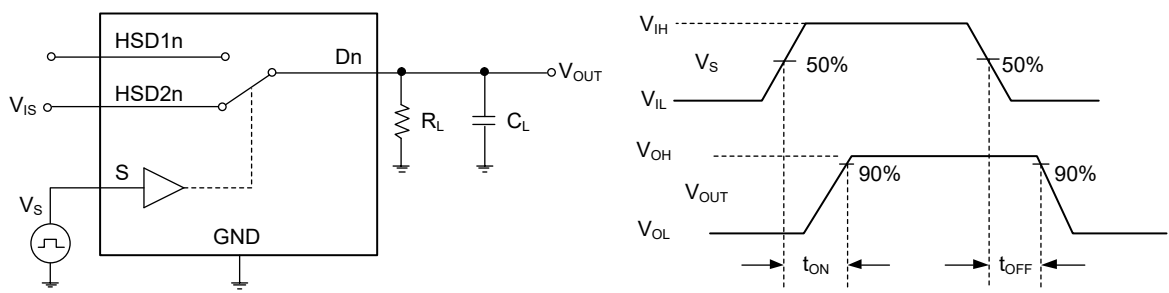
Eye Pattern: 480Mbps USB 2.0 Signal with Switch NC Path



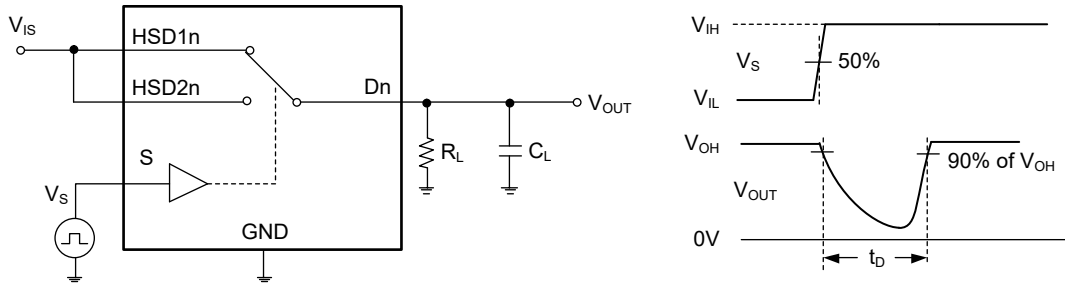
TEST CIRCUITS



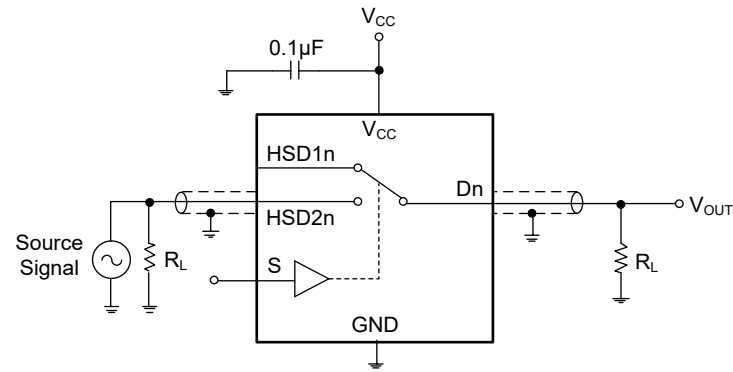
Test Circuit 1. On-Resistance



Test Circuit 2. Switching Times (t_{ON} , t_{OFF})

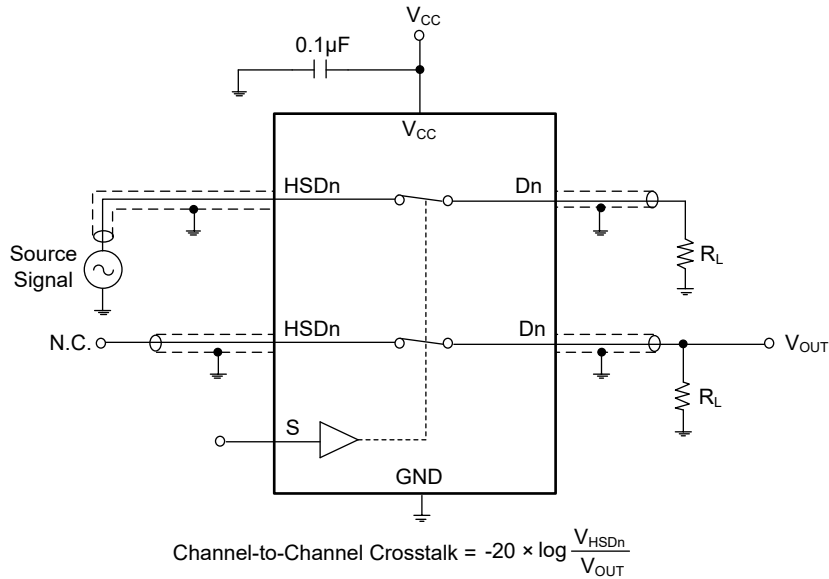


Test Circuit 3. Break-Before-Make Time Delay (t_D)

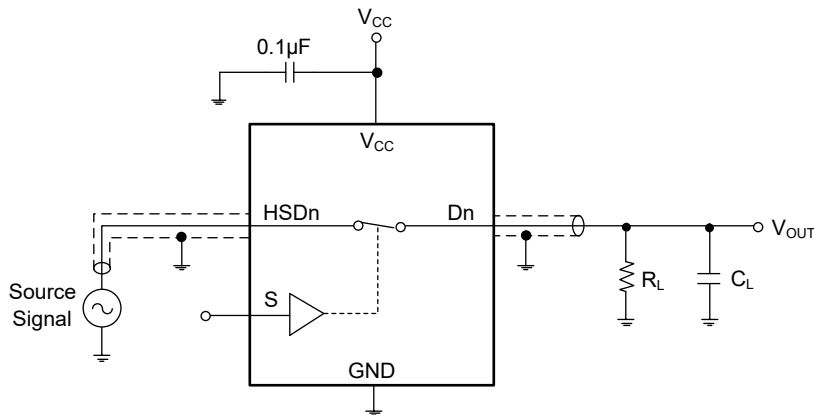


Test Circuit 4. Off Isolation

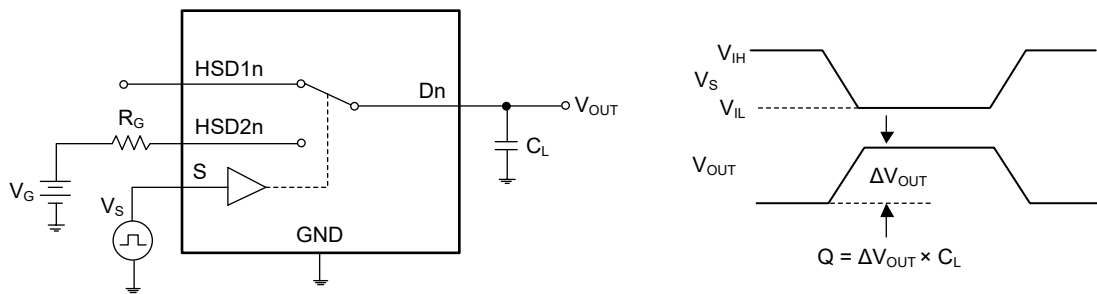
TEST CIRCUITS (continued)



Test Circuit 5. Channel-to-Channel Crosstalk



Test Circuit 6. -3dB Bandwidth



Test Circuit 7. Charge Injection (Q)

APPLICATION NOTES

Meeting USB 2.0 V_{BUS} Short Requirements

Power-Off Protection

For a V_{BUS} short circuit, the switch is expected to withstand such a condition for at least 24 hours. The SGM7229 has specially designed circuitry which prevents unintended signal bleeding through as well as guarantees system reliability during a power-down, over-voltage condition. The protection has been added to the common pins (D+, D-).

Power-On Protection

The USB 2.0 specification also notes that the USB device should be capable of withstanding a V_{BUS} short during transmission of data. This modification works by limiting current flow back into the V_{CC} rail during the over-voltage event so current remains within the safe operating range.

REVISION HISTORY

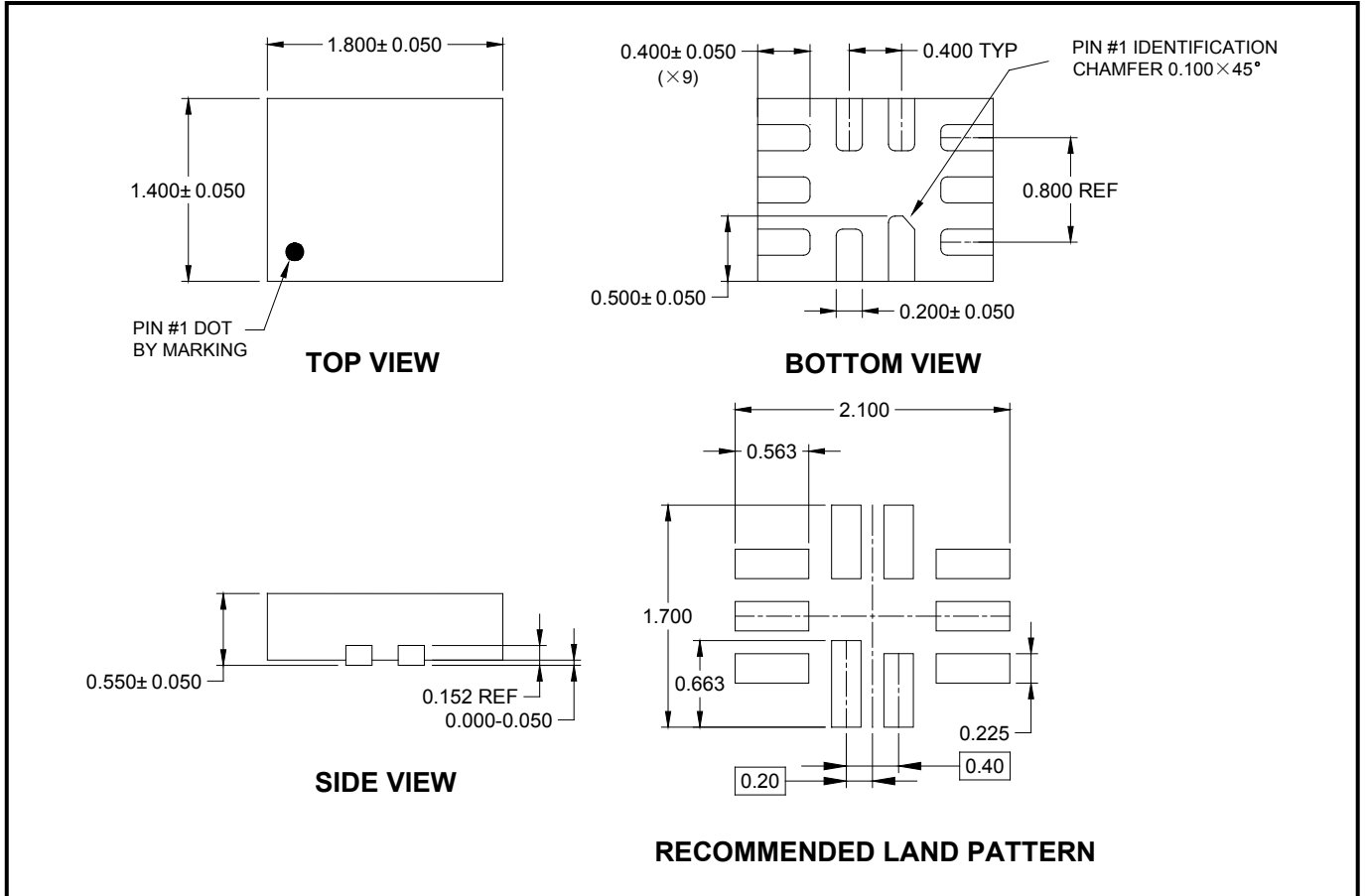
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Original (DECEMBER 2018) to REV.A

Changed from product preview to production data All

PACKAGE OUTLINE DIMENSIONS

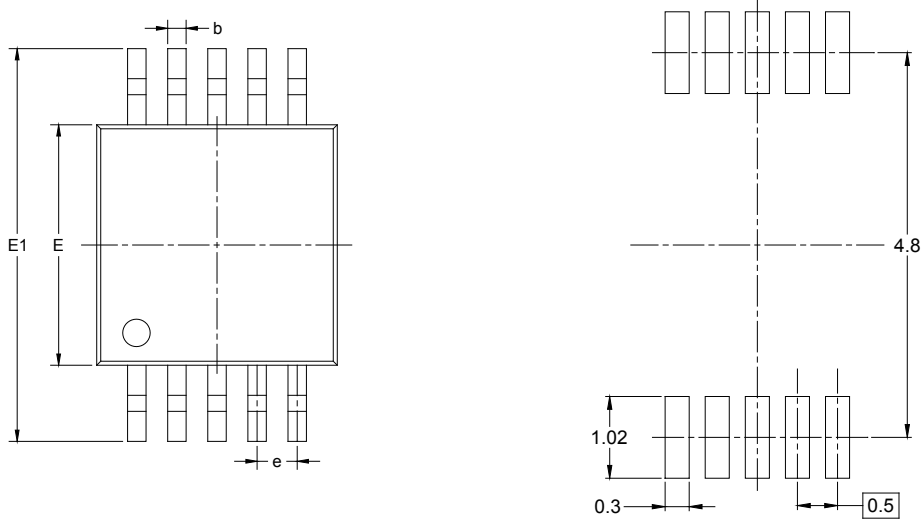
UTQFN-1.8×1.4-10L



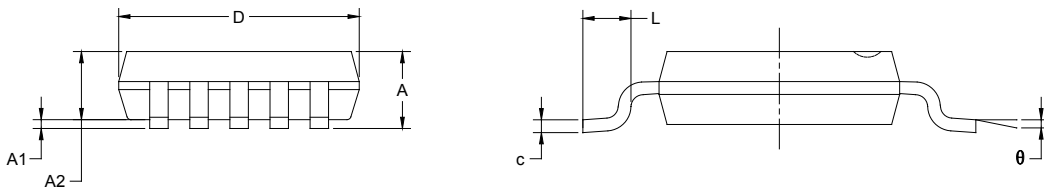
NOTE: All linear dimensions are in millimeters.

PACKAGE OUTLINE DIMENSIONS

MSOP-10



RECOMMENDED LAND PATTERN (Unit: mm)

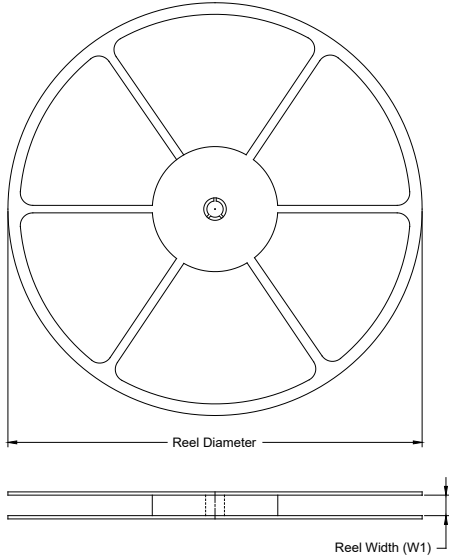


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	0.820	1.100	0.032	0.043
A1	0.020	0.150	0.001	0.006
A2	0.750	0.950	0.030	0.037
b	0.180	0.280	0.007	0.011
c	0.090	0.230	0.004	0.009
D	2.900	3.100	0.114	0.122
E	2.900	3.100	0.114	0.122
E1	4.750	5.050	0.187	0.199
e	0.500 BSC		0.020 BSC	
L	0.400	0.800	0.016	0.031
θ	0°	6°	0°	6°

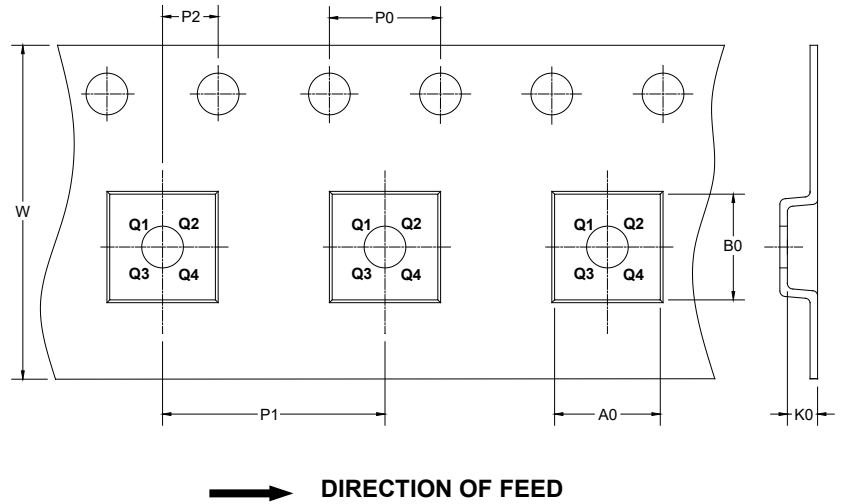
PACKAGE INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
UTQFN-1.8×1.4-10L	7"	9.0	1.75	2.10	0.70	4.0	4.0	2.0	8.0	Q1
MSOP-10	13"	12.4	5.20	3.30	1.20	4.0	8.0	2.0	12.0	Q1

D00001

PACKAGE INFORMATION

CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
7" (Option)	368	227	224	8
7"	442	410	224	18
13"	386	280	370	5

DD0002